L	Hits	Search Text	DB	Time stamp
Number			ľ	-
1	2175	Via near15 contact\$3 near15 (through or thru) near15 (chip or wafer or substrate)	USPAT; US-PGPUB;	2003/05/15 10:12
			EPO; JPO; DERWENT; IBM TDB	
2	5920	(slop\$3 or taper\$3) near5 via	USPAT;	2003/05/15
		·	US-PGPUB; EPO; JPO; DERWENT;	10:13
			IBM TDB	
3	130796	(front or top) near10 (wafer or substrate	USPAT;	2003/05/15
		or chip)	US-PGPUB;	10:15
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	127681	(	USPAT;	2003/05/15
		substrate or chip)	US-PGPUB;	10:16
			EPO; JPO;	
			DERWENT;	
5	36968	((front or top) near10 (wafer or	IBM_TDB	2002/05/15
J	30300	((liont of top) hearto (water or   substrate or chip)) same ((back or	USPAT;	2003/05/15
		bottom) near10 (wafer or substrate or	US-PGPUB; EPO; JPO;	10:16
		chip))	DERWENT;	
			IBM TDB	
6	39	(Via near15 contact\$3 near15 (through or	USPAT;	2003/05/15
_		thru) near15 (chip or wafer or	US-PGPUB;	10:16
		substrate)) and ((slop\$3 or taper\$3)	EPO; JPO;	
		near5 via) and (((front or top) near10	DERWENT;	
		(wafer or substrate or chip)) same ((back	IBM TDB	
		or bottom) near10 (wafer or substrate or	_	
		chip)))		

L Number	Hits	Search Text	DB	Time stamp
1	2175	Via near15 contact\$3 near15 (through or thru) near15 (chip or wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/15 10:12
2	5920	(slop\$3 or taper\$3) near5 via	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/05/15 10:13
3	130796	(front or top) near10 (wafer or substrate or chip)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/15 10:15
4	127681	(back or bottom) near10 (wafer or substrate or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/15 10:16
5	36968	<pre>((front or top) near10 (wafer or substrate or chip)) same ((back or bottom) near10 (wafer or substrate or chip))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:16
6	39	(Via near15 contact\$3 near15 (through or thru) near15 (chip or wafer or substrate)) and ((slop\$3 or taper\$3) near5 via) and ((front or top) near10 (wafer or substrate or chip)) same ((back or bottom) near10 (wafer or substrate or chip)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15
7	817	(contact\$3 adj4 pad) near15 ((back or bottom) near10 (wafer or substrate or chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/15 10:38
8	12848	contact near15 ((front or top) near10 (wafer or substrate or chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/15 10:39
9	262	<pre>((contact\$3 adj4 pad) near15 ((back or bottom) near10 (wafer or substrate or chip))) same (contact near15 ((front or top) near10 (wafer or substrate or chip)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/15 10:39
10	0	<pre>(((contact\$3 adj4 pad) near15 ((back or bottom) near10 (wafer or substrate or chip))) same (contact near15 ((front or top) near10 (wafer or substrate or chip)))) and ((slop\$3 or taper\$3) near5 via)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:40
11	54	(((contact\$3 adj4 pad) near15 ((back or bottom) near10 (wafer or substrate or chip))) same (contact near15 ((front or top) near10 (wafer or substrate or chip)))) and (Via near15 contact\$3 near15 (through or thru) near15 (chip or wafer or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:40
12	8	<pre>((((contact\$3 adj4 pad) near15 ((back or bottom) near10 (wafer or substrate or chip))) same (contact near15 ((front or top) near10 (wafer or substrate or chip)))) and (Via near15 contact\$3 near15 (through or thru) near15 (chip or wafer or substrate))) and (slop\$3 or taper\$3)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/15 10:43

13	32 ((((contact\$3 adj4 pad) near15 ((back or	USPAT;	2003/05/15
	bottom) near10 (wafer or substrate or	US-PGPUB;	10:43
	chip))) same (contact near15 ((front or	EPO; JPO;	
	top) near10 (wafer or substrate or	DERWENT;	
İ		IBM TDB	
	(through or thru) near15 (chip or wafer	_	
	or substrate))) and (via adj5 contact)		